



MAS-FIN-153

*Image*

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By: 

Date: February 18, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No. : 10/090,289 Confirmation No. 6619  
Applicant : Johann Winderl  
Filed : March 4, 2002  
TC/A.U. : 2827  
Examiner : Luan C. Thai  
Title: : Electronic Component with Stacked  
Semiconductor Chips  
  
Docket No. : MAS-FIN-153  
Customer No. : 24131

Hon. Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**SUPPLEMENTAL AMENDMENT**

S i r :

Further to the amendment mailed on January 30, 2004 in response to the Office action dated January 6, 2004, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.